



28278

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : CHANG et al.
Application No. : 09/837,272 ✓
Filed : April 19, 2001
Title : DOUBLE SIDED CHIP PACKAGE
Group Art Unit : 2827
Examiner : L. Cruz
Docket No. : BHT/3183-13

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Honorable Commissioner for Patents
Washington, DC 20231

TRANSMITTAL COVER SHEET

Sir:

Transmitted herewith for filing are the following:

1. AMENDMENT - in response to the Office Action of March 28, 2002, along with a version with markings indicating changes thereto.
2. LETTER TO THE OFFICIAL DRAFTSPERSON, along with one (1) sheet of corrected formal drawings (Figure 1).
3. Petition for Three-Month Extension of Time and check for \$920.00.

The Commissioner is hereby authorized to charge any fees which may be required for the filing of this document to Deposit Account No. 501874.

Respectfully submitted,

Date: September 27, 2002

By:

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#6/A
10-8-02
Muller
Attorney Docket: BHT/3183-13

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AMENDMENT

Sir:

In response to the Office Action of March 28, 2002, the period for response to which has been extended to expire on **September 28, 2002** by the filing herewith of a Petition for a three-month extension of time and payment of the required fee, please amend the above-identified application as follows:

IN THE SPECIFICATION:

The following new paragraphs have been inserted between prenumbered lines 23 and 24 of page 2:

--BRIEF DESCRIPTION OF THE DRAWINGS

A'

Figure 1: A cross-sectional view of the structure of the double sided chip package in U.S. patent number 6,118,176;

Figure 2: A cross-sectional view of the double sided chip package of a first embodiment in the present invention;

Figure 3: A top view of the double sided chip package of a first embodiment before molding in the present invention;